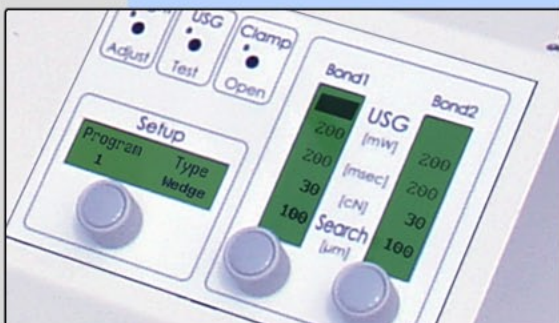
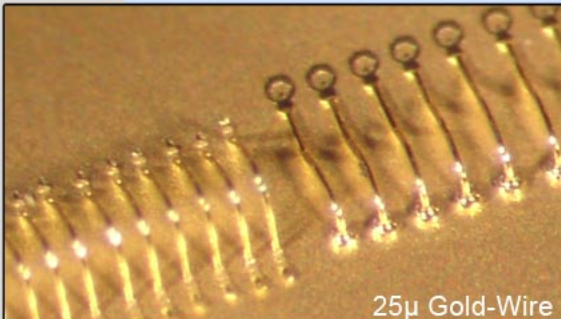




# HB10 Wedge and Ball Bonder



- + Wedge, Ball and Bump bonding
- + 17µ to 50µ Wire and 25µ x 200µ Ribbon
- + Digital Control with LCD Display
- + Deep-access Bond Head 16 mm
- + Bond arm length 165 mm
- + 20 Program storage capacities
- + Heater stage & Tool Heater Controller
- + Built in Dual Fiber Optic illuminator
- + Motorised Z Bond Head
- + Motorized 2" Wire Spool Holder
- + 6:1 ratio X-Y manipulator
- + Electronic ball size control
- + Loop Height Programmable
- + Semi-auto and Manual Bonding Mode

# HB10 Thermosonic Wire Bonder for Wedge & Ball & Bump Bonding

The HB10 is a bench top size wire bonder, easy to operate and ideal for laboratories. pilot and pre-production runs and small scale production lines. One Bond head for bonding in Wedge/Wedge, Ball/Wedge or Bump bonding mode. No hardware change necessary. Direct access and simple adjustment to all bond parameters and programs.

## Standard

Digital Control with LCD Display  
90° Bonding Deep-access Bond Head  
PLL Ultrasonic generator  
Loop Height programmable  
Large bonding area  
Stitch bonding  
Bond arm length 165 mm  
20 Program storage capacities  
Built in Dual Fiber Optic illuminator  
Built in Heater stage & Toll Heater Controller  
Motorised 2" Wire Spool  
Motorised Z  
Semi-automatic and manual bonding  
Electronic ball size control

## Options

H10 Zoom Stereo-Microscope Leica S6 20x  
H21 100 x 100 mm Adjustable height heated work stage  
H26 Adjustable height heated work stage surface 60 mm ø  
H29 Adjustable height heated work stage surface 90 mm ø  
H50 Spot light targeting System  
H60 Bonding tool for Wedge bonding 25µ wire  
H61 Bonding tool for Ball Bonding 25µ wire  
H70 Gold-Wire 25µ, 60 Meter, 2" Spool  
H74 Aluminium -Wire 25µ, 60 Meter, 2" Spool  
H72 ½ " Wire Spool adapter  
H73 Torque Wrench 25 cNm for Bonding Tool  
H90 Delivery with installation and user Training

## Technical Specifications

Ultrasonic system	PLL Control 62 kHz transducer
Ultrasonic power	0 - 1 watt Low / 0 - 2 watt High output
Bond time	15 - 2000 msec.
Bond force	15 - 150 cNm
Bonding Tool	1,58 Dia. X 19 mm length (0,0624" Dia. x 0,750")
Gold wire diameter	17 to 50µ ( 0,7 to 2 mil )
Aluminium wire diameter	17 to 50µ ( 0,7 to 2 mil )
Gold ribbon	up to 25 x 200µ ( 1x 8 mil)
Motorised Wire Spool	50,8 mm ( 2 inch )
Wire termination	Bond Head tear
Wire feed angle	90° for Wire and Ribbon
Motorized Z travel	15 mm (0,6")
Throat depth	165 mm ( 6,7")
Fine Table motion	15 mm (0,55 ")
Mouse ratio	6:1
Temperature controller	up to 250°C +/- 1°C
Electrical Requirements	100 - 240V +/-10% 50/60 Hz 10A max.
Physical Dimensions	680 mm ( 27")W x 640 mm (25") D x 490 mm ( 19") H
Weight	Shipping 60 kg Net 45 kg
Industry Standards	CE standards



TPT Franz Hickmann  
Lärchenweg 59a  
D-85757 Karlsfeld  
Tel.: +49 (0) 8131 / 58604  
Fax: +49 (0) 8131 / 58654  
www.tpt.de